

SOCKET APPARATUS FOR SEMICONDUCTOR DEVICES

Abstract of the Disclosure

A socket (2) mounts contact pins (13), each of which has contact parts (14, 15) received in a respective slit (32) formed by partitions (31), each contact part (14) having an enlarged width at its tip. When a semiconductor device (200) is inserted into the socket (2), contact parts (14, 15) of each pair serially engage with a respective terminal lead so that the semiconductor device (200) is ready for electrical testing. According to the invention, the distance between respective contact parts (14) is less than the width of the terminal leads, thus the terminal leads (202) do not become entangled with the contact parts (14) upon inserting or removing a semiconductor device into or out of the socket. The upper distal portion of the partition (31) have a reduced thickness to provide clearance for receipt of the contact part (14). A second embodiment shows a socket (3) having contact pins (43) having enlarged contact tips (44) along with trigger follower parts 42 and a movable cover having a cam (57). A third embodiment shows a socket (4) having contact pins (73) having enlarged contact tips (74) arranged on four sides of a semiconductor device seating portion (88).

Figure 1